

Helping Customers Innovate, Improve & Grow

Table 1. Electrical Performance			_				
Parameter	Symbol	Min.	Тур	Max	Units		
Nominal Frequency	F _{NOM}	8.000		60.000	MHz		
Mode		Fundan					
Operating Temperature Range	T _{OP}	0/70, -	°C				
Stability Over T _{OP} ¹	F _{STAB}	±10		±100	ppm		
Frequency Tolerance ²	F _{TOL}		±10	ppm			
Load Capacitance	C _L	6		pF			
Shunt Capacitance	C _o		5		рF		
Drive Level			10	100	uW		
Aging / 1st year (at 25 °C)	F _{AGE}			±5	ppm		
Insulation Resistance		500			MOhm		
Storage Temperature	T _{sto}	-40		90	°C		
Equivalent Series Resistance							
Crystal Frequency 8.000MHz-12.000MHz 12.001MHz-16.000MHz 16.001MHz-20.000MHz 20.001MHz-60.000MHz	ESR			100 80 70 50	Ohm		

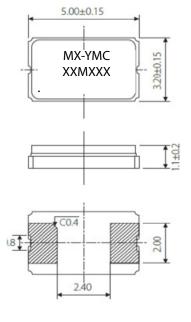
Notes:

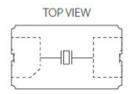
- 1. Referenced to the Frequency at 25 °C.
- 2. Frequency measured at 25 °C \pm 3 °C.

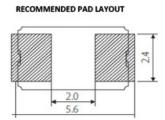
Product is compliant to RoHS directive and fully compatible with lead free assembly.



Package Drawing







All Dimensions in mm

Part Marking:

MX = VXM1 Product Family

Y = Year

M = Month

A = January

B = February

C = March

D = April

E = May

F = June

G = July

H = August I = September

J = October

K = November

L = December

C = Manufacuting Location XXMXXX = frequency

Table 2. Environmental Compliance							
Parameter	Conditions						
Mechanical Shock	MIL-STD-883, Method 2002, Condition B						
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A						
Temperature Cycle	MIL-STD-883, Method 1010, Condition B						
Solderability	MIL-STD-202-210, Condition B						
Gross and Fine Leak	MIL-STD-883, Method 1014						
Altitude	MIL-STD-883, Method 1001, Condition B						
Moisture Sensitivity Level	MSL 1						
Contact Pads	Gold (0.3 um min) over Nickel						
Weight	38 mg						

Reliability & IR Compliance

Solderprofile:

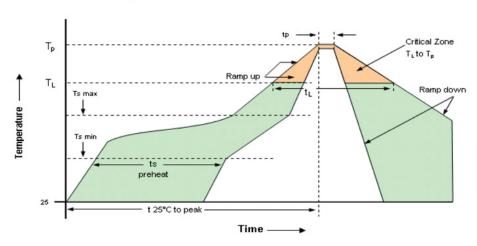
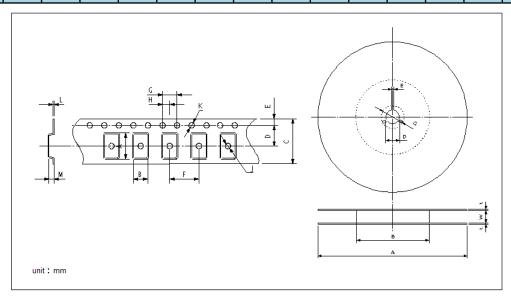


Table 2: Reflow Profile								
Parameter	Symbol	Value						
PreHeat Time Ts-min Ts-max	t _s	60 sec Min, 260 sec Max 150°C 200°C						
Ramp Up	R_{UP}	3 °C/sec Max						
Time Above 217 °C	t _L	60 sec Min, 150 sec Max						
Time To Peak Temperature	T_{AMB-P}	480 sec Max						
Time at 260 °C	t _p	30 sec Max						
Ramp Down	R _{DN}	6 °C/sec Max						

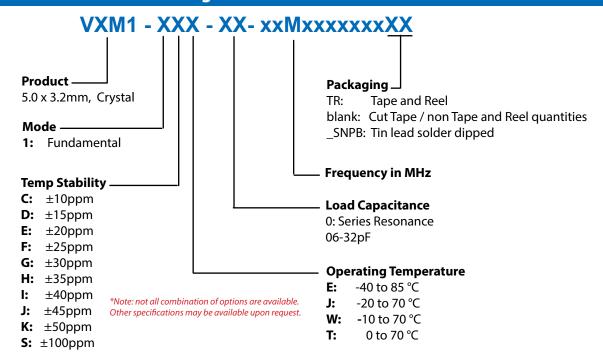
Pads are Au over Ni and compatible with either SnPb or Pb free attachment. MSL: 1

Tape & Reel

Table	Table 7. Tape and Reel Dimensions (mm)																	
Tape												Reel						
Α	В	С	D	Е	F	G	Н	J	K	L	М	Α	В	С	D	Е	W	Т
5.25	3.45	12.0	5.5	1.75	8.0	4.0	2.0	1.5	1.5	0.3	1.1	178	180	21.0	13.0	2.0	12.4	2.0



Ordering Information



Example:

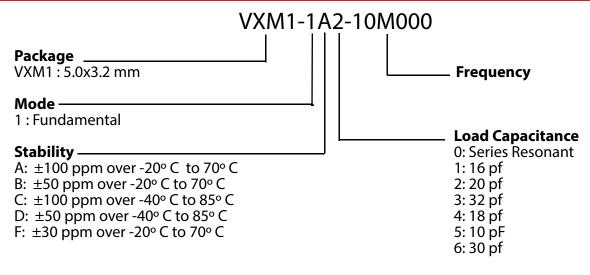
VXM1-1EE-12-25M0000000TR Tape and Reel VXM1-1EE-12-25M0000000 Cut Tape

VXM1-1EE-12-25M0000000_SNPB Tin lead solder dipped

Revision History

Revision Date	Approved	Description
August 29, 2016	RC	Initial datasheet for factory approval and release to customer.
August 10, 2018	FB	Update logo and contact infromation, add "SNPBDIP" ordering option
June 07, 2019	FB	Update logo and contact information, add Table 2 Environmental compliance, change "SNPBDIP" to "SNPB"
April 30, 2020	FB	Add tape and reel ordering option

Previous Ordering Information for Reference Only Do Not Use to Build a New Part Number



The ordering codes for the VXM1 were changed in 2016. If you had ordered a specific code based off this ordering method, it is still available for purchase under the old code however no new part numbers will be created using this system.

Due to the change in the 8th character from numeric to alphabetic, there is no opportunity for overlap between the two ordering methods.

Contact Information

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